

N-Channel 100V(D-S) MOSFET

Product summary		
V_{DS}	100	V
$R_{DS(ON)}$ (at $V_{GS}=10V$) Typ.	95	m Ω
$R_{DS(ON)}$ (at $V_{GS}=4.5V$) Typ.	100	m Ω
I_D ($T_A=25^\circ C$)	3	A

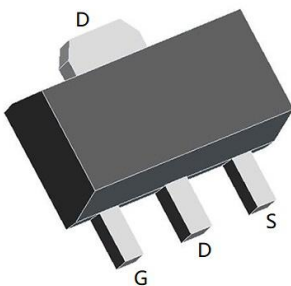
Features

- High density cell design for low $R_{DS(ON)}$
- Trench Power MV MOSFET technology
- RoHS Compliant

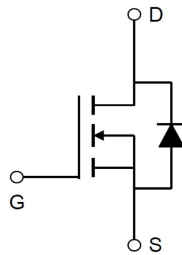
Applications

- DC-DC Converters
- Power management functions

Pin Configuration



SOT-89



Packing Information

Device	Marking	Reel Size	Quantity(Min. Package)
ECDL03N10A	1003.	7"	1000pcs

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current at $V_{GS}=10V$	$T_A=25^\circ C$	3
		$T_A=70^\circ C$	2.4
I_{DM}	Pulse Drain Current Tested ^A	12	A
P_D	Power Dissipation	$T_C=25^\circ C$	1.5
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient ^B	83	$^\circ C/W$

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D =250uA	100	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V,V _{GS} =0V	--	--	1	uA
I _{GSS}	Gate-Body Leakage Current	V _{DS} =0V,V _{GS} =±20V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250uA	1.0	1.8	3.0	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V,I _D =3A	--	95	110	mΩ
		V _{GS} =4.5V,I _D =2.4A	--	100	120	mΩ
V _{SD}	Forward Voltage	I _{SD} =3A,V _{GS} =0V	--	--	1.2	V
Dynamic Parameters						
C _{iss}	Input Capacitance	V _{GS} =0V,V _{DS} =50V f=1MHZ	--	790	--	pF
C _{oss}	Output Capacitance		--	39	--	pF
C _{rss}	Reverse Transfer Capacitance		--	31	--	pF
Switching Parameters						
Q _g	Total Gate Charge	V _{DS} =50V,I _D =3A V _{GS} =10V	--	16	--	nC
Q _{gs}	Gate-Source Charge		--	2.5	--	nC
Q _{gd}	Gate-Drain Charge		--	2.6	--	nC
t _{D(on)}	Turn-on Delay Time	V _{DD} =50V R _L =6.4Ω,R _{GEN} =3Ω, V _{GS} =10V	--	5.5	--	nS
t _r	Turn-on Rise Time		--	42	--	nS
t _{D(off)}	Turn-off Delay Time		--	22	--	nS
t _f	Turn-off Fall Time		--	8	--	nS

A. Pulse Test: Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 1 inch x 0.062 inch.

Typical Characteristics

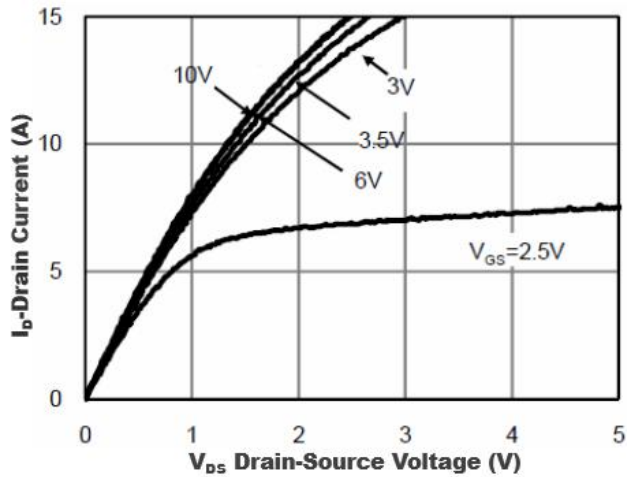


Figure1. Output Characteristics

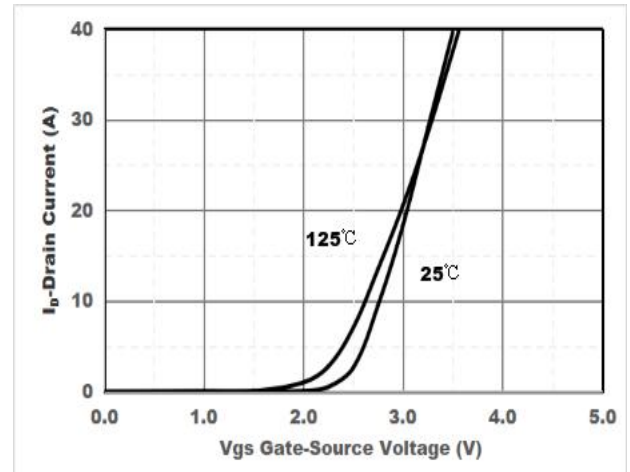


Figure2. Transfer Characteristics

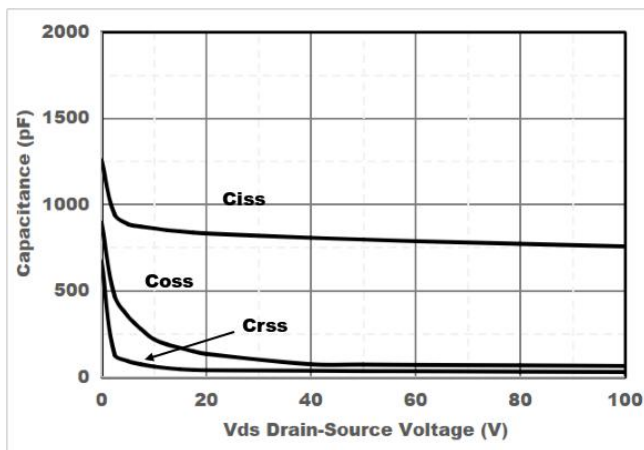


Figure3. Capacitance Characteristics

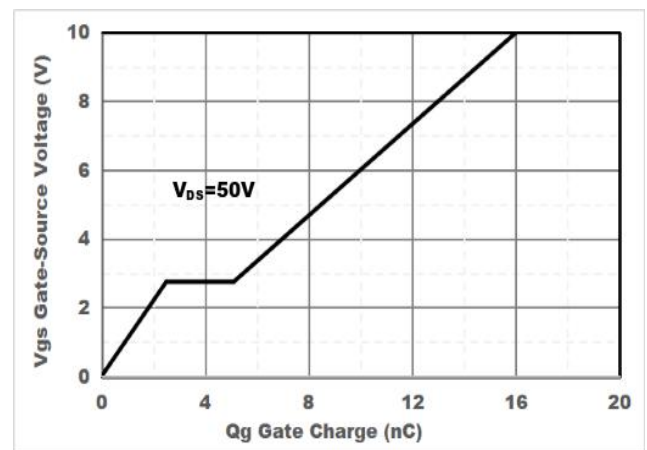


Figure4. Gate Charge

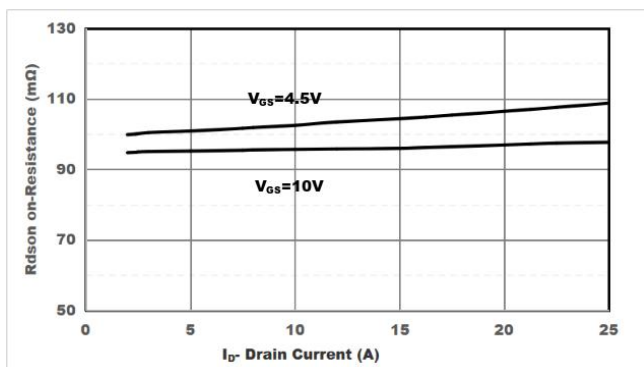


Figure5. Drain-Source on Resistance

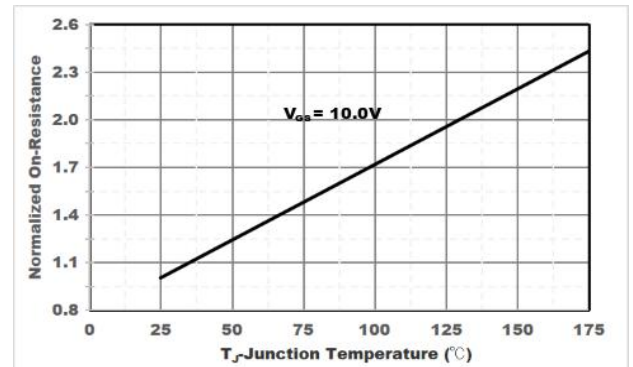


Figure6. Drain-Source on Resistance

Typical Characteristics

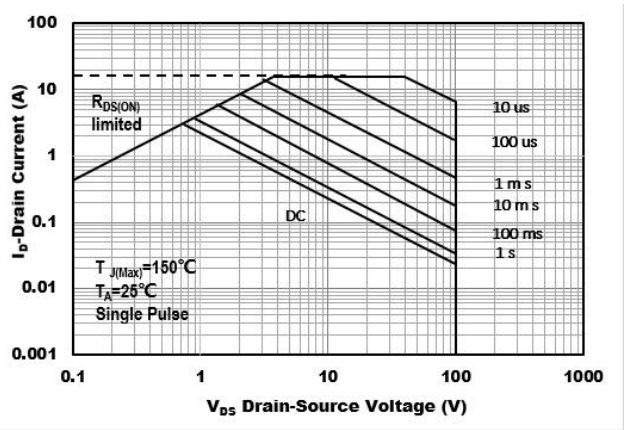


Figure7. Safe Operation Area

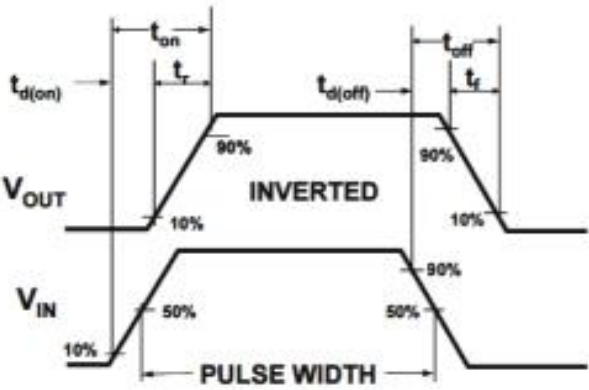
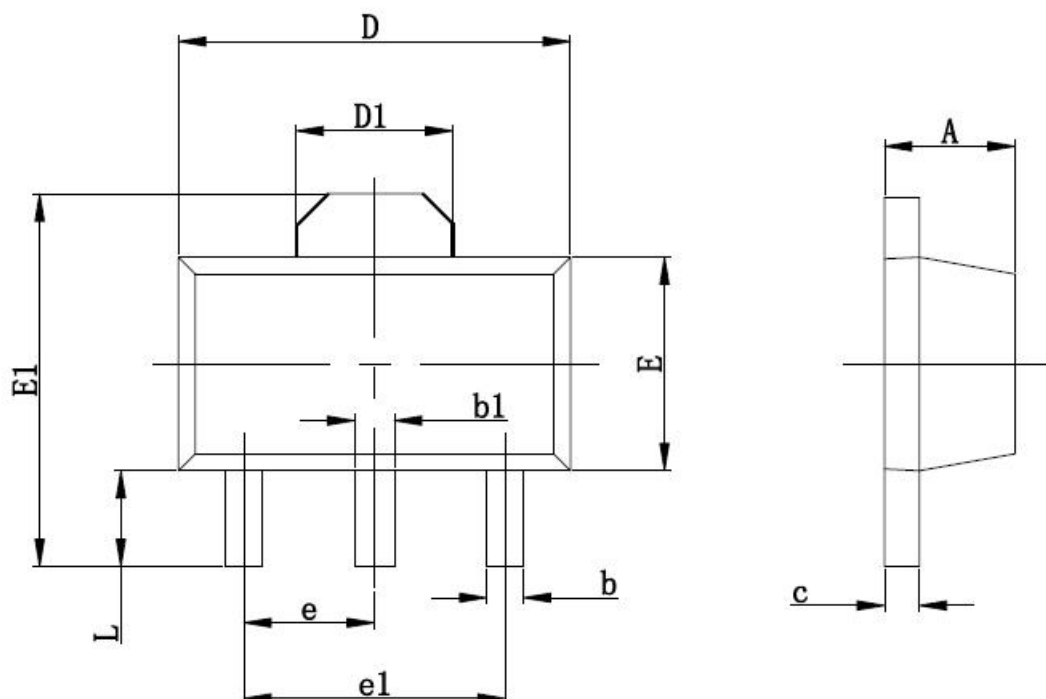


Figure8. Switching wave

SOT-89 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.350	0.520	0.013	0.197
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF		0.061 REF	
E	2.350	2.550	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP		0.060TYP	
e1	3.000 TYP		0.118TYP	
L	0.900	1.100	0.035	0.047